


**PRODUCT / PROCESS CHANGE INFORMATION**

**1. PCI basic data**

<b>1.1 Company</b>		STMicroelectronics International N.V
<b>1.2 PCI No.</b>	AMS/20/11952	
<b>1.3 Title of PCI</b>	New MBD and Assembly process settings for LDLN025 in package VFDFPN 1x1 4L assembled in CARSEM – CHINA	
<b>1.4 Product Category</b>	See product list	
<b>1.5 Issue date</b>	2020-02-13	

**2. PCI Team**

<b>2.1 Contact supplier</b>	
<b>2.1.1 Name</b>	ROBERTSON HEATHER
<b>2.1.2 Phone</b>	+1 8475853058
<b>2.1.3 Email</b>	heather.robertson@st.com
<b>2.2 Change responsibility</b>	
<b>2.2.1 Product Manager</b>	Marcello SAN BIAGIO
<b>2.1.2 Marketing Manager</b>	Salvatore DI VINCENZO
<b>2.1.3 Quality Manager</b>	Sergio Tommaso SPAMPINATO

**3. Change**

<b>3.1 Category</b>	<b>3.2 Type of change</b>	<b>3.3 Manufacturing Location</b>
Methods	Process flow chart: Revision change in Process (process technology, sawing, die attach, plasma, capillary, marking, packing, labelling, transportation, etc..)	Assembly : Subcontractor Carsem (China)

**4. Description of change**

	<b>Old</b>	<b>New</b>
<b>4.1 Description</b>	New settings on Bonding placement, Wafer sawing, Die attach, Wire bond, Mold Package sawing. Please refer to the qualification report for all the details.	New settings on Bonding placement, Wafer sawing, Die attach, Wire bond, Mold Package sawing. Please refer to the qualification report for all the details.
<b>4.2 Anticipated Impact on form, fit, function, quality, reliability or processability?</b>	No impact	

**5. Reason / motivation for change**

<b>5.1 Motivation</b>	This change will contribute to ST's continuous service and quality improvement of the product and prevent potential quality issues.
<b>5.2 Customer Benefit</b>	QUALITY IMPROVEMENT

**6. Marking of parts / traceability of change**

<b>6.1 Description</b>	New finished good codes
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**7. Timing / schedule**

<b>7.1 Date of qualification results</b>	2020-02-11
<b>7.2 Intended start of delivery</b>	2020-03-28
<b>7.3 Qualification sample available?</b>	Not Applicable

**8. Qualification / Validation**

<b>8.1 Description</b>	11952 PCI_Assembly improvement plan in CARSEM SZ for LDLN025PUxx.pdf		
<b>8.2 Qualification report and qualification results</b>	Available (see attachment)	<b>Issue Date</b>	2020-02-13

**9. Attachments (additional documentations)**

11952 Public product.pdf  
11952 PCI\_Assembly improvement plan in CARSEM SZ for LDLN025PUxx.pdf

**10. Affected parts**

10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	LDLN025PU18R	
	LDLN025PU28R	
	LDLN025PU29R	
	LDLN025PU30R	

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## Public Products List

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**PCI Title** : New MBD and Assembly process settings for LDLN025 in package VFDFPN 1x1 4L assembled in CARSEM – CHINA

**PCI Reference** : AMS/20/11952

**Subject** : Public Products List

Dear Customer,

Please find below the Standard Public Products List impacted by the change.

LDLN025PU18R	LDLN025PU29R	LDLN025PU28R
LDLN025PU30R		



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